

AMENDMENT TO THE CLAIMS

Please withdraw claims 26-28, amend claims 29, 30, and 43, and add new claims 44-48, as follows:

1-25. (Cancelled)

26. (Withdrawn) A method of bonding a first body to a second body comprising the steps of:

disposing between the first body and the second body, a reactive multilayer foil and at least one meltable joining material, the reactive multilayer foil having a plurality of openings through the thickness of the foil;

pressing the bodies together against the foil and the joining material; and

igniting the reactive foil to melt the joining material and permit the melted material to flow through the openings to join the first and second bodies.

27. (Withdrawn) The method of claim 26 wherein at least one of first body or the second body comprise a semiconductor or a microelectronic device.

28. (Withdrawn) The method of claim 26 wherein the first body and the second body have CTEs that differ by more than about $1\mu\text{m}/\text{m}/^\circ\text{C}$.

29. (Currently Amended) ~~The~~ A product made by ~~the~~ a method of claim 26 bonding a first body to a second body comprising the steps of:

disposing between the first body and the second body, a reactive multilayer foil and at least one meltable joining material, the reactive multilayer foil having a plurality of openings through the thickness of the foil;

pressing the bodies together against the foil and the joining material; and

igniting the reactive foil to melt the joining material and permit the melted material to flow through the openings to join the first and second bodies.

30. (Currently Amended) The product ~~made by the method~~ of claim 27 29, wherein at least one of the first body and the second body comprises a semiconductor.

31-42. (Cancelled)

43. (Currently Amended) A bonded structure comprising:

a first body; and

a second body bonded to the first body by a joining region, the joining region comprising a reacted multilayer foil structure including a periodic array of openings therethrough, the foil structure embedded in a matrix of meltable joining material extending through the openings to join the first body and the second body.

44. (New) The structure of claim 43, wherein at least one of the first body and the second body comprises a microelectronic device.

45. (New) The structure of claim 43, wherein at least one of the first body and the second body comprises a semiconductor.

46. (New) The structure of claim 43, wherein the first body and the second body have CTEs that differ by more than about $1\mu\text{m}/\text{m}/^{\circ}\text{C}$.

47. (New) The product of claim 29, wherein at least one of the first body and the second body comprises a microelectronic device.

48. (New) The product of claim 29, wherein the first body and the second body have coefficients of thermal expansion (CTEs) that differ by more than about $1\mu\text{m}/\text{m}/^{\circ}\text{C}$.